SamHop Microelectronics Corp.

SP6719

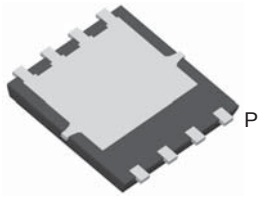
Ver 1.0

N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V_{DSS}	I_D	$R_{DS(ON)}$ (mΩ) Max
60V	11A	12.5 @ VGS=10V
		19.0 @ VGS=4.5V

FEATURES

- Super high dense cell design for low $R_{DS(ON)}$.
- Rugged and reliable.
- Suface Mount Package.



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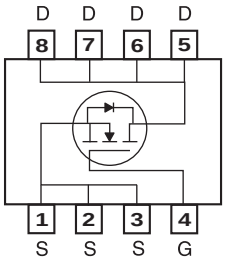


ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise noted)

Symbol	Parameter		Limit	Units
V_{DS}	Drain-Source Voltage		60	V
V_{GS}	Gate-Source Voltage		±20	V
I_D	Drain Current-Continuous [c]	T_A=25°C	11	A
		T_A=70°C	8.8	A
I_{DM}	-Pulsed [a c]		39	A
E_{AS}	Single Pulse Avalanche Energy [d]		256	mJ
P_D	Maximum Power Dissipation	T_A=25°C	3.1	W
		T_A=70°C	2	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range		-55 to 150	°C

THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	40	°C/W

ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	60			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=48V , V_{GS}=0V			1	uA
I_{GSS}	Gate-Body Leakage Current	V_{GS}= ±20V , V_{DS}=0V			±100	nA
ON CHARACTERISTICS						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} , I_D=250uA	1	2	3	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	V_{GS}=10V , I_D=5.5A		10	12.5	m ohm
		V_{GS}=4.5V , I_D=4.5A		14	19.0	m ohm
g_{FS}	Forward Transconductance	V_{DS}=10V , I_D=5.5A		22		S
DYNAMIC CHARACTERISTICS [b]						
C_{ISS}	Input Capacitance	V_{DS}=25V,V_{GS}=0V f=1.0MHz		2525		pF
C_{OSS}	Output Capacitance			236		pF
C_{RSS}	Reverse Transfer Capacitance			195		pF
SWITCHING CHARACTERISTICS [b]						
$t_{D(ON)}$	Turn-On Delay Time	V_{DD}=30V I_D=1A V_{GS}=10V R_{GEN}= 6 ohm		49		ns
t_r	Rise Time			63		ns
$t_{D(OFF)}$	Turn-Off Delay Time			122		ns
t_f	Fall Time			25		ns
Q_g	Total Gate Charge	V_{DS}=30V,I_D=5.5A,V_{GS}=10V		39		nC
		V_{DS}=30V,I_D=5.5A,V_{GS}=4.5V		20		nC
Q_{gs}	Gate-Source Charge	V_{DS}=30V,I_D=5.5A, V_{GS}=10V		4		nC
Q_{gd}	Gate-Drain Charge			11		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V_{SD}	Diode Forward Voltage	V_{GS}=0V,I_S=2A		0.75	1.3	V

Notes

a.Pulse Test:Pulse Width ≤ 10us, Duty Cycle ≤ 1%.
b.Guaranteed by design, not subject to production testing.
c.Drain current limited by maximum junction temperature.
d.Starting T_J=25°C,L=0.5mH,V_{DD} = 30V.(See Figure13)
e.Mounted on FR4 Board of 1 inch^2 , 2oz.

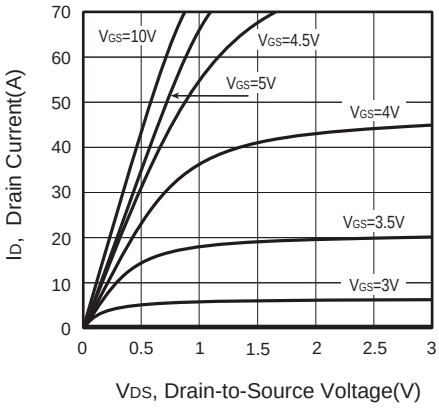


Figure 1. Output Characteristics

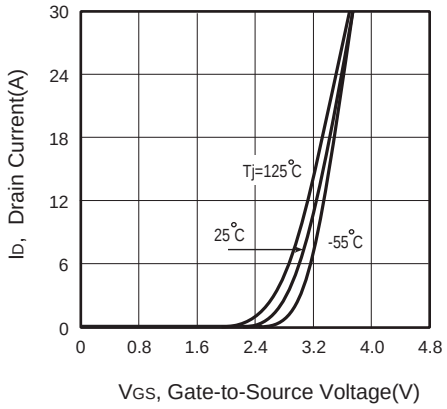


Figure 2. Transfer Characteristics

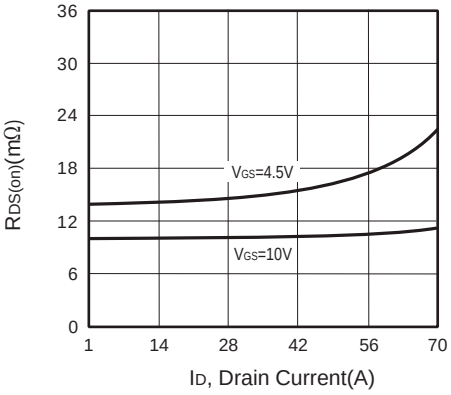


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

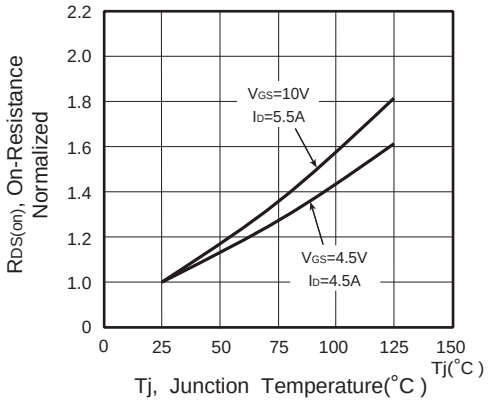


Figure 4. On-Resistance Variation with Drain Current and Temperature

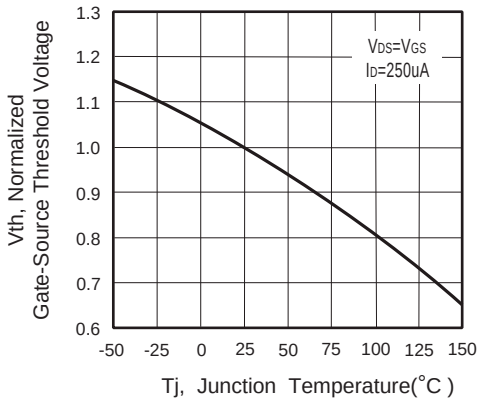


Figure 5. Gate Threshold Variation with Temperature

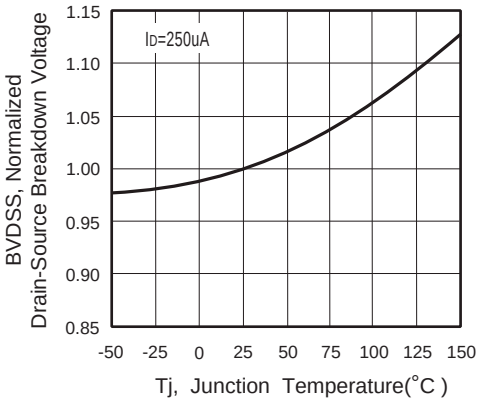


Figure 6. Breakdown Voltage Variation with Temperature

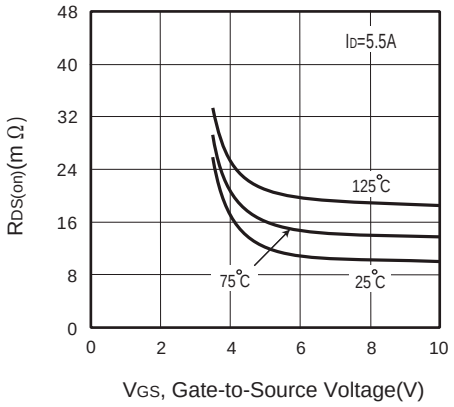


Figure 7. On-Resistance vs. Gate-Source Voltage

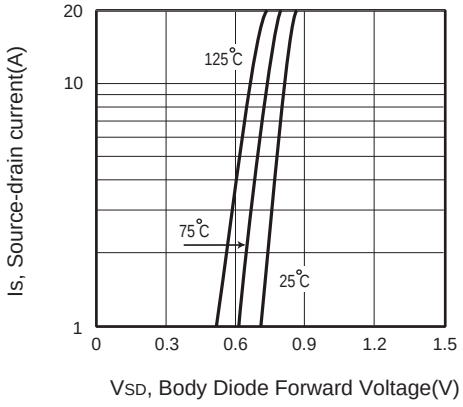


Figure 8. Body Diode Forward Voltage Variation with Source Current

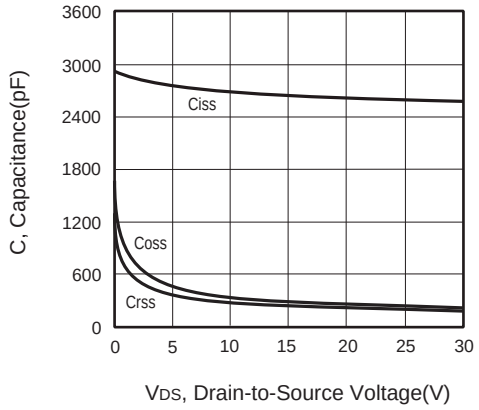


Figure 9. Capacitance

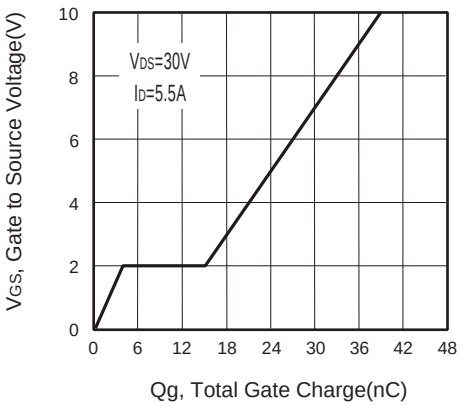


Figure 10. Gate Charge

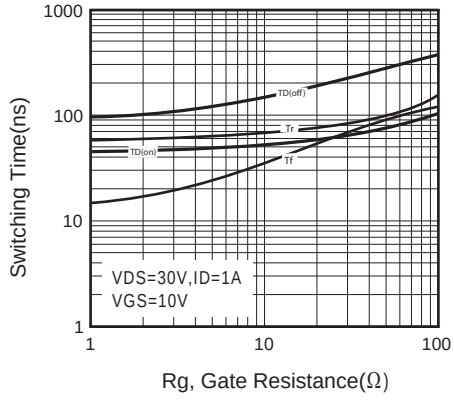


Figure 11. switching characteristics

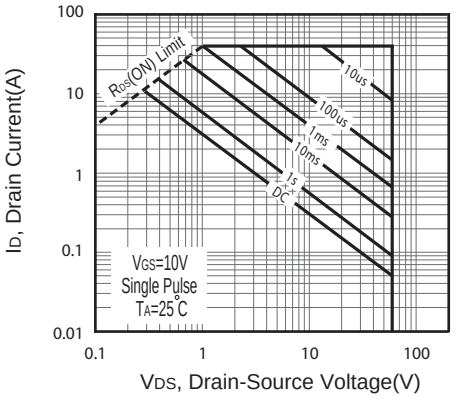
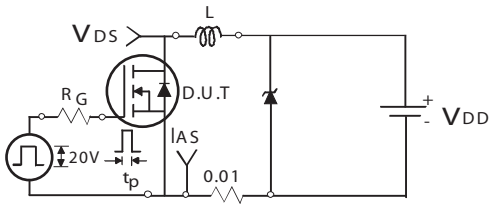
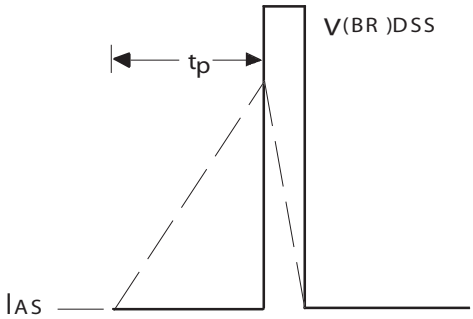


Figure 12. Maximum Safe Operating Area



Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

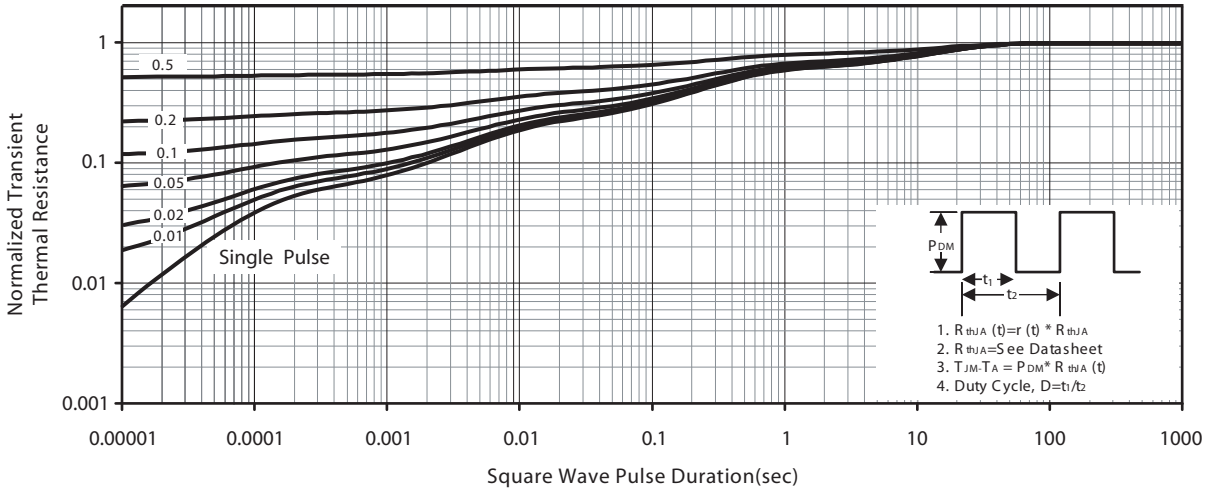


Figure 13. Normalized Thermal Transient Impedance Curve

PACKAGE OUTLINE DIMENSIONS

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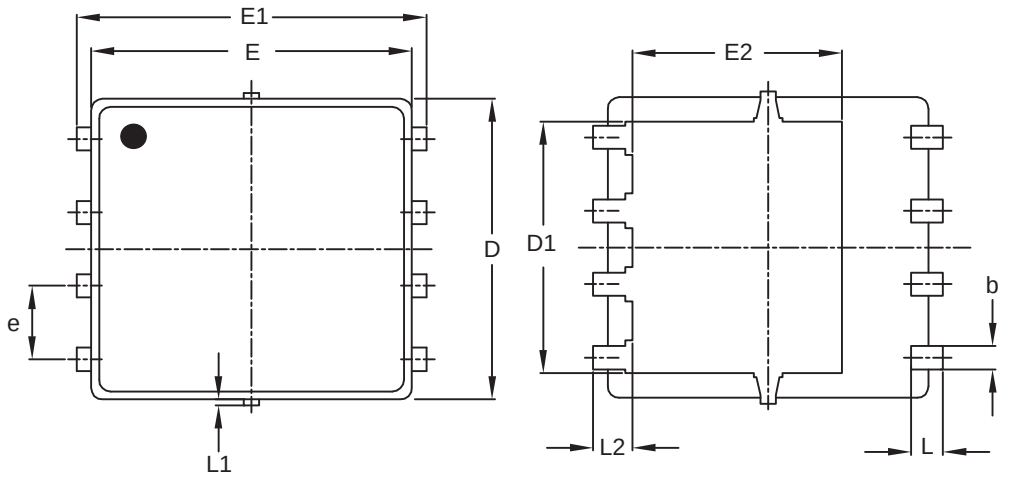

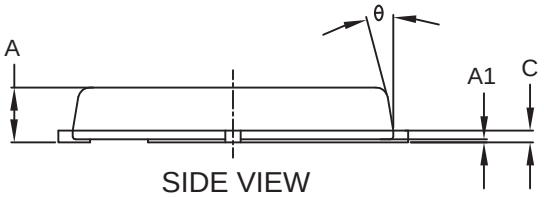

SYMBOLS	MILLIMETERS		
	MIN	NOM	MAX
A	0.85	0.95	1.00
A1	0.00	—	0.05
b	0.30	0.40	0.50
c	0.15	0.20	0.25
D		5.20 BSC	
D1		4.35 BSC	
E		5.55 BSC	
E1		6.05 BSC	
E2		3.62 BSC	
e		1.27 BSC	
L	0.45	0.55	0.65
L1	0.00	—	0.15
L2		0.68 REF	
θ	0°	—	10°

TOP MARKING DEFINITION

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